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June 2009

## FPF1015/6/7/8 IntelliMAX<sup>™</sup> 1V Rated Advanced Load Management Products

### Features

- 0.8 to 1.8V Input Voltage Range
- Typical R<sub>DS(ON)</sub> = 34mΩ @ V<sub>ON</sub> V<sub>IN</sub> = 2.0V
- Output Discharge Function
- Internal Pull down at ON Pin
- Accurate Slew Rate Controlled Turn-on time
- Low < 1µA Quiescent Current
- ESD Protected, above 8000V HBM, 2000V CDM
- RoHS Compliant
- Free from Halogenated Compounds and Antimony Oxides

PIN 1

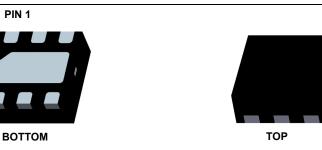
### Applications

- PDAs
- Cell Phones
- GPS Devices
- MP3 Players
- Digital Cameras
- Notebook Computers

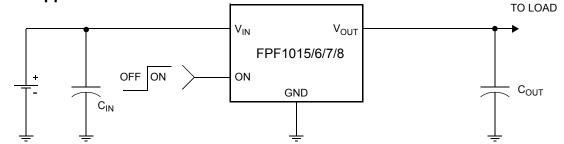


The FPF1015/6/7/8 series is an IntelliMAX advanced slew rate loadswitch offering a very low operating voltage. These devices consist of a  $34m\Omega$  N-channel MOSFET that supports an input voltage up to 2.0V. These slew rate devices control the switch turn-on and prevent excessive in-rush current from the supply rails. The input voltage range operates from 0.8V to 1.8V to fulfill today's lowest Ultraportable Device's supply requirements. Switch control is via a logic input (ON) capable of interfacing directly with low voltage control signals.

The FPF1016 and FPF1018 have an On-Chip pull down allowing for guick and controlled output discharge when switch is turned off. The FPF1015/6/7/8 series is available in a space-saving 2X2 MLP-6L package.

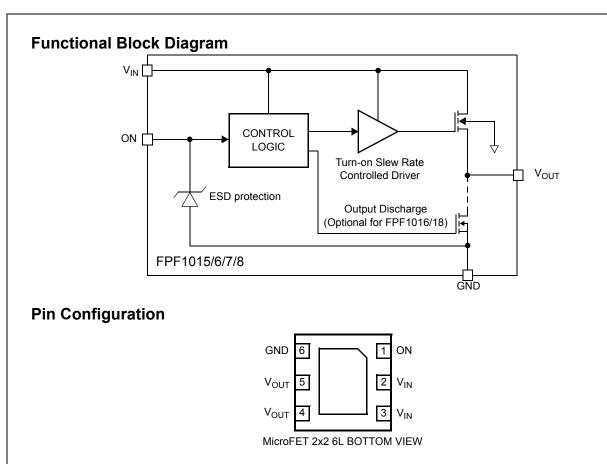


### **Typical Application Circuit**



### **Ordering Information**

Part	Switch	Turn-on Time	Output Discharge	ON Pin Activity	Package
FPF10 <sup>-</sup>	15 34mΩ, NMOS	43us	NA	Active HI	MLP 2x2
FPF10 <sup>-</sup>	16 34mΩ, NMOS	43us	60Ω	Active HI	MLP 2x2
FPF10 <sup>-</sup>	17 34mΩ, NMOS	165us	NA	Active HI	MLP 2x2
FPF10 <sup>-</sup>	18 34mΩ, NMOS	165us	60Ω	Active HI	MLP 2x2



### **Pin Description**

Pin	Name	Function
1	ON	ON/OFF Control Input, 2nd Supply
2, 3	V <sub>IN</sub>	Supply Input: Input to the power switch
4, 5	V <sub>OUT</sub>	Switch Output.
6	GND	Ground

### **Absolute Maximum Ratings**

Parameter	Min	Max	Unit	
V <sub>IN</sub> , V <sub>OUT</sub> to GND	-0.3	2	V	
V <sub>ON</sub> to GND	-0.3	4.2	V	
Maximum Continuous Switch Current		1.5	А	
Power Dissipation @ T <sub>A</sub> = 25°C (Note 1)		1.2	W	
Operating Temperature Range	-40	85	°C	
Storage Temperature	-65	150	°C	
Thermal Resistance, Junction to Ambient		86	°C/W	
Electrostatic Discharge Distoction	HBM	8000		V
Electrostatic Discharge Protection	CDM	2000		V

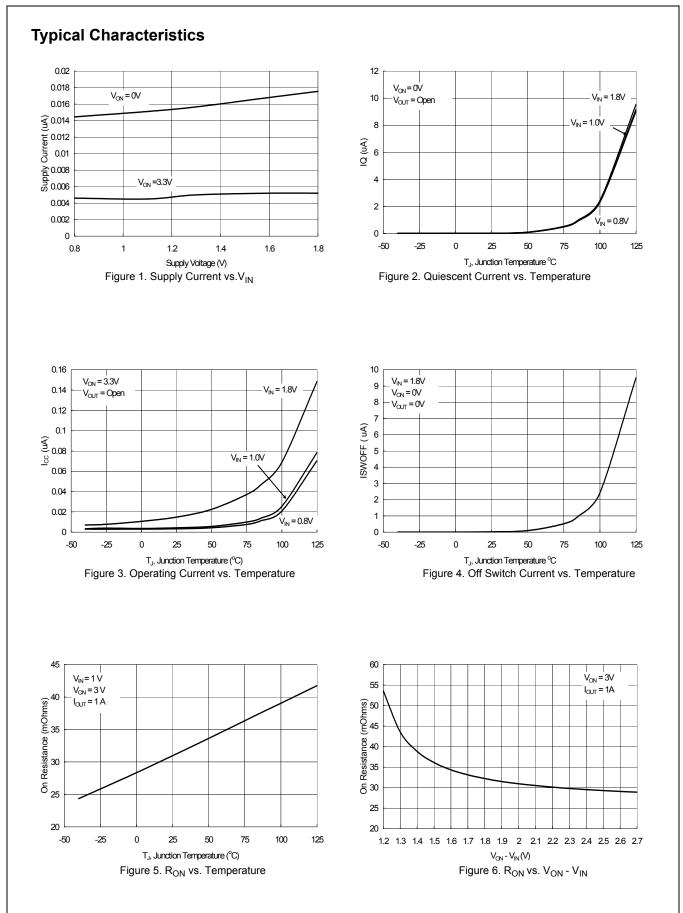
### **Recommended Operating Range**

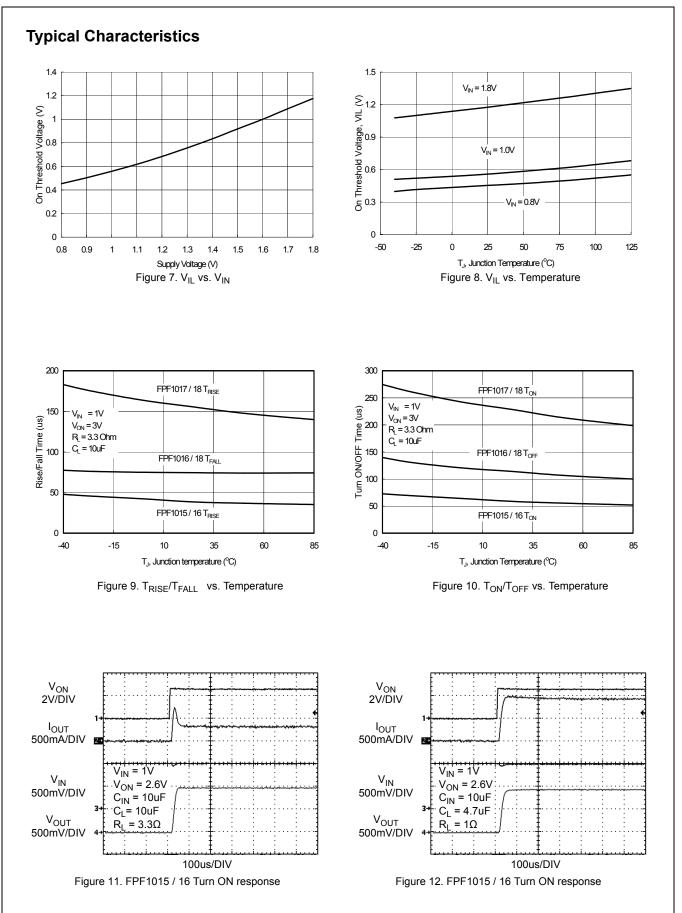
Parameter	Min	Max	Unit	
V <sub>IN</sub>	0.8	1.8	V	
Ambient Operating Temperature, T <sub>A</sub>	-40	85	°C	
Note 1: Package power dissipation on 1square inch pad, 2 oz. copper board				

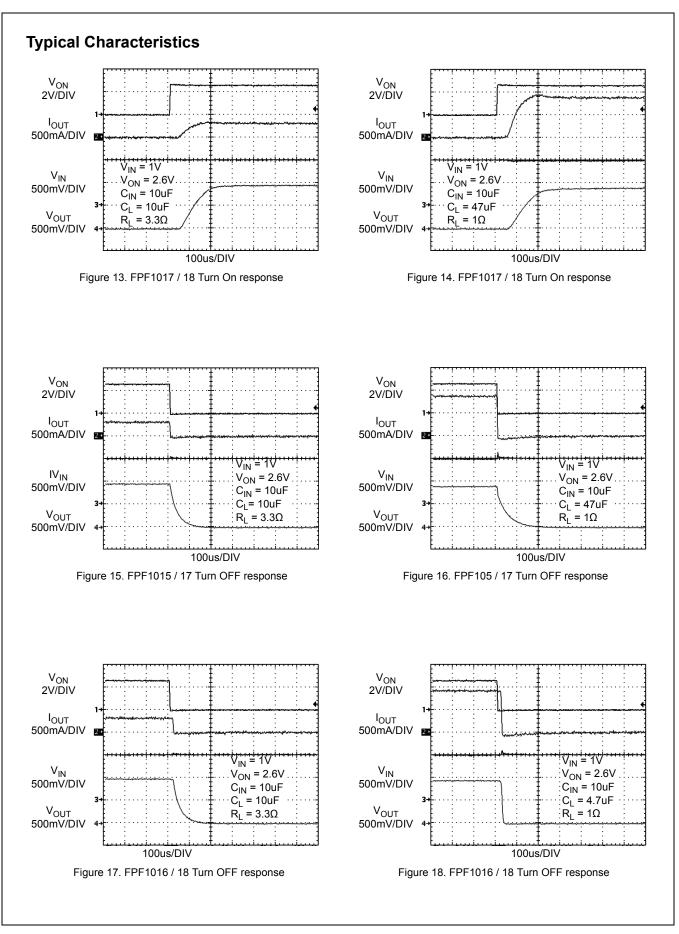
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Basic Operation					1		
Operating Voltage	V <sub>IN</sub>		0.8		1.8	V	
ON input Voltage	V <sub>ON(MIN)</sub>	V <sub>IN</sub> = 0.8V	1.8	2.8	4.0	V	
ON input Voltage	V <sub>ON(MAX)</sub>	V <sub>IN</sub> = 1.8V(Note2)	2.8	3.8	4.0	V	
Operating Current	I <sub>CC</sub>	$V_{IN}$ = 1V, $V_{ON}$ = 3.3V, $V_{OUT}$ = Open			1	μA	
Quiescent Current	Ι <sub>Q</sub>	$V_{IN}$ = 1V, $V_{ON}$ = $V_{OUT}$ = Open			2	μA	
Off Switch Current	I <sub>SWOFF</sub>	$V_{IN}$ = 1.8V, $V_{ON}$ = GND, $V_{OUT}$ = GND			2	μA	
On-Resistance	R <sub>ON</sub>	$V_{IN}$ = 1V, $V_{ON}$ = 3V, $I_{LOAD}$ = 1A, $T_A$ = 25°C		34	45	mΩ	
UN-RESISTANCE	''ON	$V_{IN}$ = 1V, $V_{ON}$ = 2.3V, $I_{LOAD}$ = 1A, $T_A$ = 25°C		41	55		
Output Pull Down Resistance	R <sub>PD</sub>	$V_{\rm IN}$ = 1V, $V_{\rm ON}$ = 0V, $T_{\rm A}$ = 25°C, $I_{\rm LOAD}$ = 1mA, FPF1016, FPF1018		60	120	Ω	
ON Input Logic Low Voltage	V <sub>IL</sub>	$V_{IN}$ = 0.8V, $R_{LOAD}$ = 1K $\Omega$	0.3		0.3	v	
ON Input Logic Low Voltage		$V_{IN}$ = 1.8V, $R_{LOAD}$ = 1K $\Omega$			0.8	v	
ON Input Leakage		V <sub>ON</sub> = V <sub>IN</sub> or GND	-1		1	μA	
<b>Dynamic</b> (V <sub>IN</sub> = 1.0V, V <sub>ON</sub> = 3	.0V, T <sub>A</sub> = 25°	C)					
		FPF1015, FPF1016, $R_L$ = 500Ω, $C_L$ = 0.1µF		28		116	
	T <sub>R</sub>	FPF1017, FPF1018, $R_L$ = 500Ω, $C_L$ = 0.1µF		114			
V <sub>OUT</sub> Rise Time		FPF1015, FPF1016, R <sub>L</sub> = 3.3Ω, C <sub>L</sub> = 10μF		38		μs	
		FPF1017, FPF1018, R <sub>L</sub> = 3.3Ω, C <sub>L</sub> = 10μF		155			
	T <sub>ON</sub>	FPF1015, FPF1016, $R_L$ = 500Ω, $C_L$ = 0.1µF		43			
		FPF1017, FPF1018, R <sub>L</sub> = 500Ω, C <sub>L</sub> = 0.1μF		165		μs	
Turn ON		FPF1015, FPF1016, R <sub>L</sub> = 3.3Ω, C <sub>L</sub> = 10μF		58			
		FPF1017, FPF1018, R <sub>L</sub> = 3.3Ω, C <sub>L</sub> = 10μF		228			
	T <sub>F</sub>	FPF1015, FPF1017, $R_L$ = 500Ω, $C_L$ = 0.1µF		105			
		FPF1016, FPF1018, R <sub>PD</sub> = 60Ω, R <sub>L</sub> = 500Ω, C <sub>L</sub> = $0.1\mu$ F		15		μs	
V <sub>OUT</sub> Fall Time		FPF1015, FPF1017, R <sub>L</sub> = 3.3Ω, C <sub>L</sub> = 10μF		80			
		FPF1016, FPF1018 R <sub>PD</sub> = 60Ω, R <sub>L</sub> = $3.3Ω$ , C <sub>L</sub> = $10μF$		74		1	
	_	FPF1015, FPF1017, R <sub>L</sub> = 500Ω, C <sub>L</sub> = 0.1μF	150				
T		FPF1016, FPF1018 R <sub>PD</sub> = 60Ω, R <sub>L</sub> = 500Ω, C <sub>L</sub> = $0.1\mu$ F		53			
Turn Off	T <sub>OFF</sub>	FPF1015, FPF1017, R <sub>L</sub> = 3.3Ω, C <sub>L</sub> = 10μF		102	μs		
		FPF1016, FPF1018 R <sub>PD</sub> = 60Ω, R <sub>L</sub> = 3.3Ω, C <sub>L</sub> = 10μF		96			

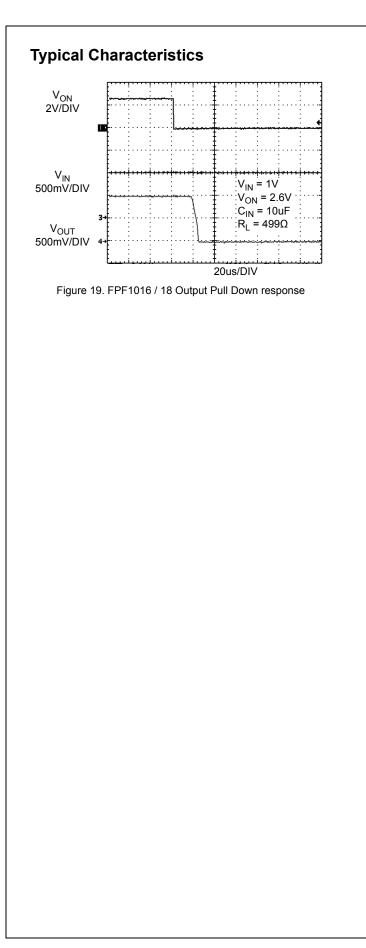
FPF1015/6/7/8 IntelliMAX<sup>™</sup> 1V Rated Advanced Load Management Products

Note 2:  $V_{ON(MAX)}$  is limited by the absolute rating.









### **Description of Operation**

The FPF1015/6/7/8 are low  $R_{DS(ON)}$  N-Channel load switches with controlled turn-on. The core of each device is a  $34m\Omega$  (V<sub>IN</sub> = 1V, V<sub>ON</sub> = 3V) N-Channel MOSFET and is customized for a low input operating range of 0.8 to 1.8V. The ON pin controls the state of the switch.

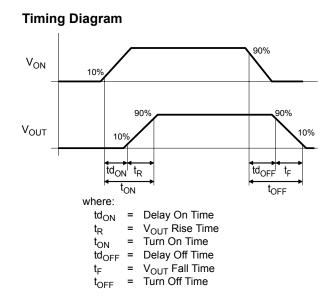
The FPF1016 and FPF1018 contain a  $60\Omega(typ)$  on-chip resistor which is connected internally from  $V_{OUT}$  to GND for quick output discharge when the switch is turned off.

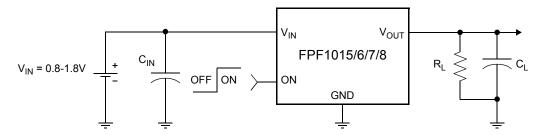
#### **On/Off Control**

The ON pin is active high and it controls the state of the switch. Applying a continuous high signal will hold the switch in the ON state. In order to minimize the switch on resistance, the ON pin voltage should exceed the input voltage by 2V. This device is compatible with a GPIO (General Purpose Input/Output) port, where the logic voltage level can be configured to  $4V \ge V_{ON} \ge V_{IN}+2V$  and power consumed is less than 1µA in steady state.

### **Application Information**

#### **Typical Application**





#### **Input Capacitor**

To limit the voltage drop on the input supply caused by transient in-rush currents when the switch turns-on, a capacitor must be placed between V<sub>IN</sub> and GND. For minimized voltage drop, especially when the operating voltage approaches 1V and a fast slew rate part (FPF1015 and FPF1016) is selected, a 10µF ceramic capacitor should be placed close to the V<sub>IN</sub> pins. Higher values of C<sub>IN</sub> can be used to further reduce the voltage drop during higher current modes of operation.

#### **Output Capacitor**

A 0.1µF capacitor, C<sub>L</sub>, should be placed between V<sub>OUT</sub> and GND. This capacitor will prevent parasitic board inductance from forcing V<sub>OUT</sub> below GND when the switch turns-off. If the application has a capacitive load, the FPF1016 and FPF1018 can be used to discharged that load through an on-chip output discharge path.

#### **Board Layout**

For best performance, all traces should be as short as possible. To be most effective, the input and output capacitors should be placed close to the device to minimize the effects that parasitic trace inductances may have on normal and short-circuit operation. Using wide traces or large copper planes for all pins (V<sub>IN</sub>, V<sub>OUT</sub>, ON and GND) will help minimize the parasitic electrical effects along with minimizing the case to ambient thermal impedance.

#### Improving Thermal Performance

An improper layout could result in higher junction temperature. This concern applies when the current is at its continuous maximum value and is then switched into a large capacitive load that introduces a large transient current. Since the FPF1015/6/7/8 does not have thermal shutdown capability, a proper layout is essential to improving power dissipation of the switch in transient events and prevents the switch from exceeding the maximum absolute power dissipation of 1.2W.

The following techniques have been identified to improve the thermal performance of this family of devices. These techniques are listed in order of the significance of their impact.

1. Thermal performance of the load switch can be improved by connecting pin7 of the DAP (Die Attach Pad) to the GND plane of the PCB.

2. Embedding two exposed through-hole vias into the DAP (pin7) provides a path for heat to transfer to the back GND plane of the PCB. A drill size of Round, 14 mils (0.35mm) with 1-ounce copper plating is recommended to result in appropriate solder reflow. A smaller size hole prevents the solder from penetrating into the via, resulting in device lift-up. Similarly, a larger via-hole consumes excessive solder, and may result in voiding of the DAP.

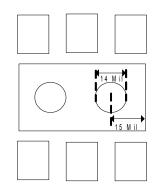


Figure 19: Two through hole open vias embedded in DAP

3. The V<sub>IN</sub>, V<sub>OUT</sub> and GND pins will dissipate most of the heat generated during a high load current condition. The layout suggested in Figure 20 provides each pin with adequate copper so that heat may be transferred as efficiently as possible out of the device. The ON pin trace may be laid-out diagonally from the device to maximize the area available to the ground pad. Placing the input and output capacitors as close to the device as possible also contributes to heat dissipation, particularly during high load currents.

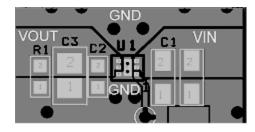


Figure 20: Proper layout of output, input and ground copper area

#### **Demo Board Layout**

FPF1015/6/7/8 Demo board has the components and circuitry to demonstrate FPF1015/6/7/8 load switches functions. Thermal performance of the board is improved using a few techniques recommended in the layout recommendations section of datasheet.

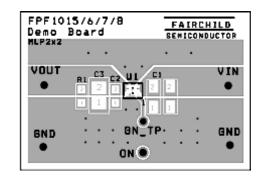
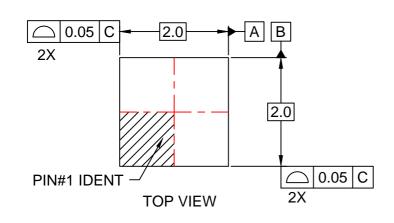
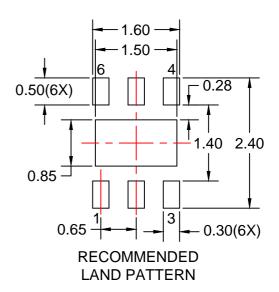
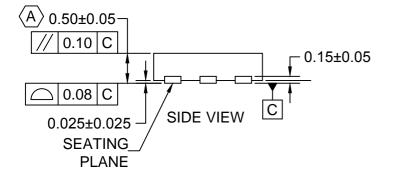
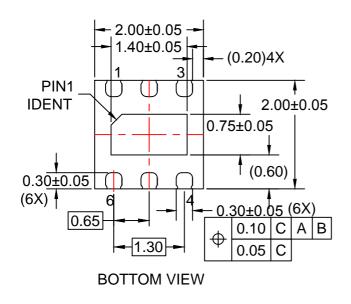


Figure 21. FPF1015/6/7/8 Demo board TOP, SST, ASTOP and DRL layers





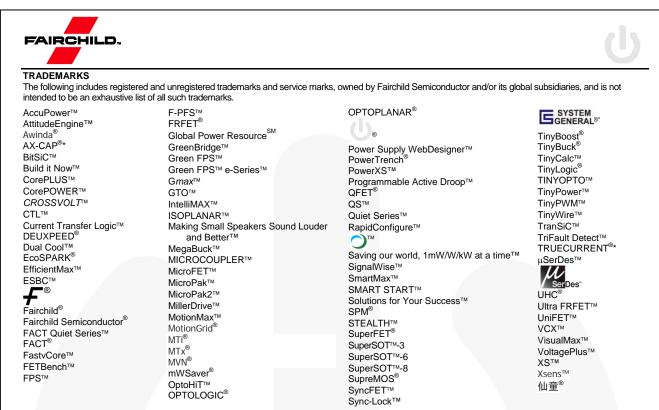




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